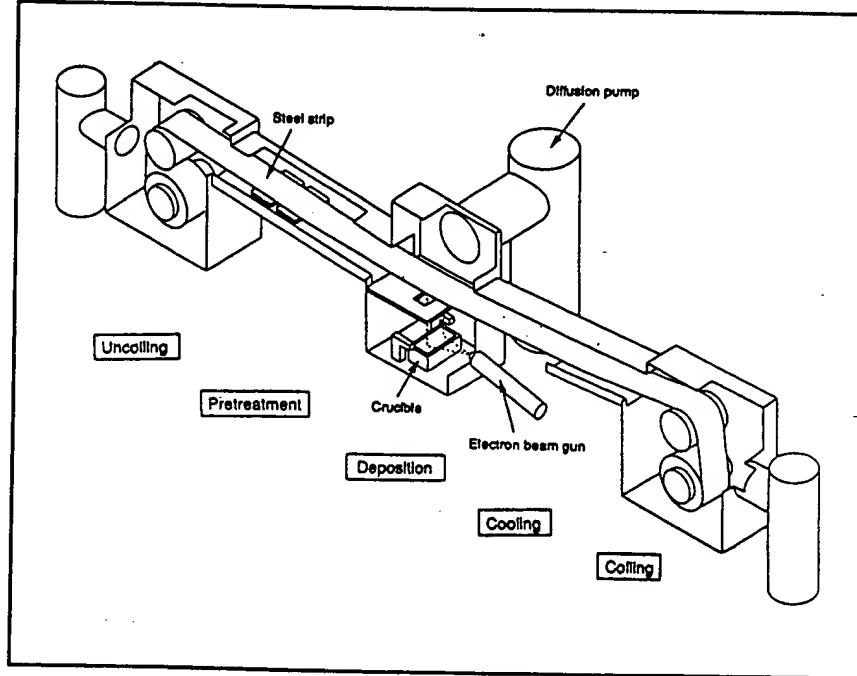


HANDBOOK OF DEPOSITION TECHNOLOGIES FOR FILMS AND COATINGS

Science, Technology
and Applications
Second Edition



Edited by
Rointan F. Bunshah

NOYES PUBLICATIONS

Appendix C

Goldwasser *et al.*
Application No.: 08/847,967

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